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Part Number: [0737827200](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits, Stack Height 6.05mm

Documents:

3D Model	Product Specification PS-73780-999-001 (PDF)
Drawing (PDF)	Packaging Specification PK-70873-0875-001 (PDF)
3D Model (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

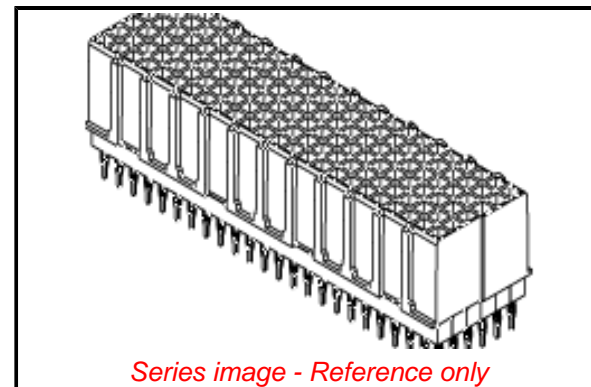
General

Product Family	Backplane Connectors
Series	73782
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800756075112

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	12.730/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole

Electrical



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
D(2021)4569-DC (8
July 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

China RoHS

Green Image

Not Relevant

Not Contained

Search Parts in this Series

[73782](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard Receptacle. [73780](#) HDM Board-to-Board Daughtercard Receptacle

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-free Process Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Packaging Specification	PK-70873-0875-001
Product Specification	PS-73780-999-001
Sales Drawing	SD-73782-001-001, SD-73782-001-002

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